



PRODUCT DATA SHEET

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Datasheet



Resources



Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

Features

- Low forward Voltage
- Designed for mounting on small surface.
- Extremely thin/leadless package.
- Majority carrier conduction.

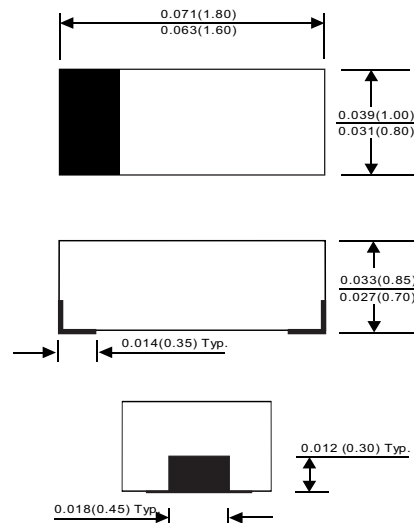
Mechanical data

- Case: SOD-523F (1608) Standard package , molded plastic.
- Terminals: Gold plated, solderable per MIL-STD-750, method 2026.

- Polarity: Indicated by cathode band.

- Mounting position: Any.

Weight: 0.003 gram (approximately).



Dimensions in inches and (millimeter)

0603(1608)

Maximum Rating (at TA = 25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
Repetitive peak reverse voltage		V _{RRM}			35	V
Reverse voltage		V _R			30	V
Average forward rectified current		I _O			200	mA
Forward current , surge peak	8.3 ms single half sine-wave superimposed on rate load (JEDEC method)	I _{FSM}			1	A
Storage temperature		T _{STG}	-40		+125	°C
Junction temperature		T _j	-40		+125	°C

Electrical Characteristics (at TA = 25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
Forward voltage	I _F = 200 mA	V _F			0.6	V
Reverse current	V _R = 10 V	I _R			1	uA

RATING AND CHARACTERISTIC CURVES

Fig. 1 - Forward characteristics

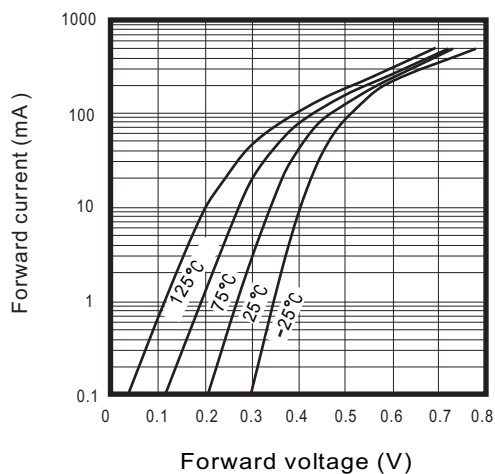


Fig. 2 - Reverse characteristics

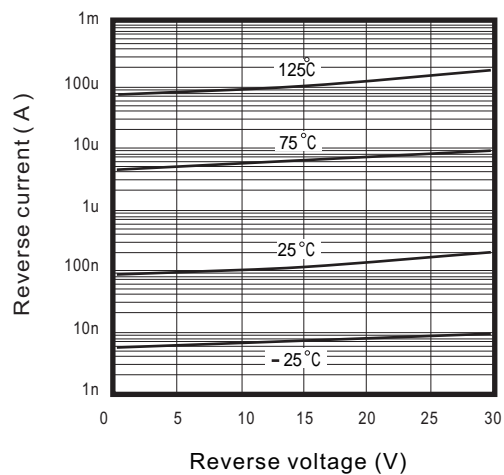


Fig. 3 - Capacitance between terminals characteristics

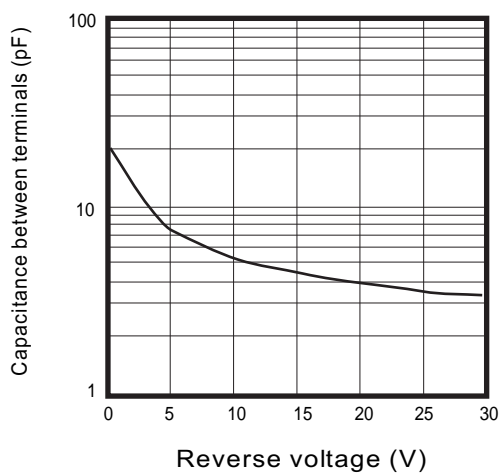
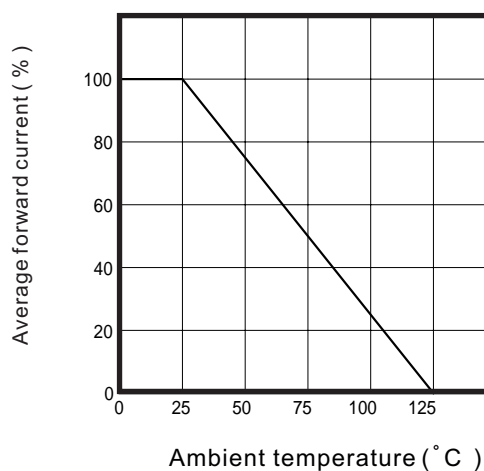


Fig. 4 - Current derating curve



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